CLAIMS

What is claimed is:

1. A resist removal method comprising:
providing a substrate having a surface;
forming resist on at least a portion of the surface; and
providing a laser to remove the resist from the substrate.

2. The method according to claim 1 wherein said laser includes a laser associated with an automolding system.

3. The method according to claim 1 wherein said laser comprises one of an Nd:YAG laser and an excimer laser.

4. The method according to claim 1 wherein said substrate comprises a ball-grid-array substrate.

5. The method according to claim 1 further comprising a vision system for detecting resist.

6. The method according to claim 5 wherein said vision system comprises:
providing a laser scanning system;
detecting changes in the pattern of the substrate.

7. A semiconductor device formed by a laser etching process comprising:
providing a substrate having a surface;
forming resist on at least a portion of the surface; and
etching the resist from the surface of the substrate using a laser.

8. The method according to claim 7 wherein said laser comprises a laser associated with an automolding system.

9. The method according to claim 7 wherein said laser includes one of an Nd:YAG laser and an excimer laser.

10. The method according to claim 7 wherein said substrate comprises a ball-grid-array substrate.

11. The method according to claim 7 further comprising a vision system for detecting resist.

12. The method according to claim 11 wherein said vision system comprises:
providing a laser scanning system;
detecting changes in the pattern of the substrate.

13. A method of fabricating a semiconductor device comprising:
providing a substrate having a surface;
forming resist on at least a portion of the surface;
laser etching the resist from the surface of the substrate; and
encapsulating the substrate.

14. The method according to claim 13 wherein said laser comprises a laser associated with an automolding system.

15. The method according to claim 13 wherein said laser comprises one of an Nd:YAG laser and an excimer laser.

16. The method according to claim 13 wherein said substrate comprises a ball-grid-array substrate.

17. The method according to claim 13 further comprising a vision system for detecting resist.

18. The method according to claim 17 wherein said vision system comprises:
providing a laser scanning system;
detecting changes in the pattern of the substrate.

19. A method of enhancing the adhesion of a compound to a surface of a substrate comprising:
providing a substrate having a surface;
roughening the surface of the substrate.

20. The method according to claim 21 wherein said roughening comprises removing contamination and foreign particles from said surface of the substrate.

21. An automolding system comprising:
providing a substrate having a surface;
preheating the substrate;
forming a resist layer;
baking the substrate; and
removing contaminants from the substrate using a laser.

22. The automolding system of claim 21 wherein said laser comprises one of an Nd:YAG laser and an excimer laser.

23. The automolding system of claim 21 further comprising:
placing the substrate in a mold; and
encapsulating the substrate.